

## Product Summary

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C
100V	62mΩ @ V <sub>GS</sub> = 10V	20A
	77mΩ @ V <sub>GS</sub> = 6V	16A

## Description

This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

## Applications

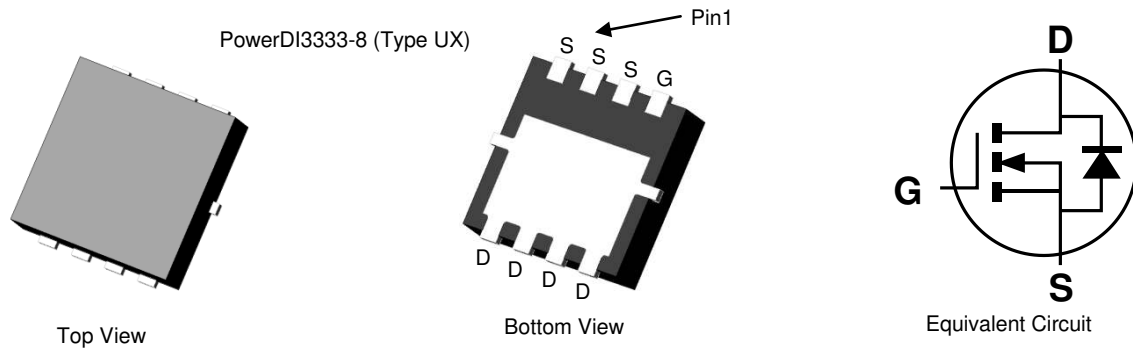
- Power Management Functions
- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.

## Features and Benefits

- Low R<sub>DS(ON)</sub> – Ensures On State Losses are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies just 33% of the Board Area Occupied by SO-8 Enabling Smaller End Product
- Low On-Resistance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**

## Mechanical Data

- Case: PowerDI<sup>®</sup> 3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish — Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 Ⓔ
- Weight: 0.072 grams (Approximate)

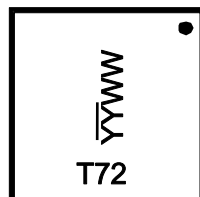


## Ordering Information (Note 4)

Part Number	Case	Quantity per Reel
DMT10H072LFV-7	PowerDI3333-8 (Type UX)	2,000/Tape & Reel
DMT10H072LFV-13	PowerDI3333-8 (Type UX)	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



T72= Product Type Marking Code  
 YYWW = Date Code Marking  
 YY = Last Two Digits of Year (ex: 19 = 2019)  
 WW = Week Code (01 to 53)

**Maximum Ratings** (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	100	V	
Gate-Source Voltage	V <sub>GSS</sub>	±20	V	
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 5)	I <sub>D</sub>	T <sub>A</sub> = +25°C	4.7	A
		T <sub>A</sub> = +70°C	3.7	A
Continuous Drain Current V <sub>GS</sub> = 10V (Note 6)	I <sub>D</sub>	T <sub>C</sub> = +25°C	20	A
		T <sub>C</sub> = +70°C	16	A
Pulsed Drain Current (10µs Pulse, T <sub>C</sub> =+25°C, Package Limited)	I <sub>DM</sub>	80	A	
Pulsed Body Diode Current (10µs Pulse, T <sub>C</sub> =+25°C, Package Limited)	I <sub>SM</sub>	80	A	
Maximum Body Diode Continuous Current	I <sub>S</sub>	2	A	
Avalanche Current (Note 9), L=0.1mH	I <sub>AS</sub>	6	A	
Avalanche Energy (Note 9), L=0.1mH	E <sub>AS</sub>	1.8	mJ	

**Thermal Characteristics** (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P <sub>D</sub>	2	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	61	°C/W
Total Power Dissipation (Note 6)	P <sub>D</sub>	37.8	W
Thermal Resistance, Junction to Case (Note 6)	R <sub>θJC</sub>	3.3	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 7)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	100	-	-	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	-	-	1	µA	V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 7)</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.5	-	2.8	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250µA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	-	50.6	62	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.5A
		-	61.2	77		V <sub>GS</sub> = 6V, I <sub>D</sub> = 4A
	R <sub>DS(ON)</sub>	-	82.5	109	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 2.7A
Diode Forward Voltage	V <sub>SD</sub>	-	0.76	1	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A
<b>DYNAMIC CHARACTERISTICS (Note 8)</b>						
Input Capacitance	C <sub>iSS</sub>	-	228	-	pF	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V, f = 1MHz
Output Capacitance	C <sub>oSS</sub>	-	89.3	-	pF	
Reverse Transfer Capacitance	C <sub>rSS</sub>	-	2.5	-	pF	
Gate Resistance	R <sub>g</sub>	-	8.2	-	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Q <sub>g</sub>	-	2.5	-	nC	V <sub>DS</sub> = 50V, I <sub>D</sub> = 4.5A
Total Gate Charge (V <sub>GS</sub> = 10V)	Q <sub>g</sub>	-	4.5	-	nC	
Gate-Source Charge	Q <sub>gs</sub>	-	0.6	-	nC	
Gate-Drain Charge	Q <sub>gd</sub>	-	1.3	-	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	-	3.0	-	ns	V <sub>DS</sub> = 50V, R <sub>L</sub> = 11Ω V <sub>GS</sub> = 10V, R <sub>GEN</sub> = 3Ω
Turn-On Rise Time	t <sub>R</sub>	-	3.1	-	ns	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	-	12.3	-	ns	
Turn-Off Fall Time	t <sub>F</sub>	-	4.3	-	ns	
Reverse Recovery Time	t <sub>RR</sub>	-	22.9	-	ns	I <sub>F</sub> = 4.5A, di/dt = 300A/µs
Reverse Recovery Charge	Q <sub>RR</sub>	-	45.2	-	nC	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
  - Thermal resistance from junction to soldering point (on the exposed drain pad).
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to product testing.
  - I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.

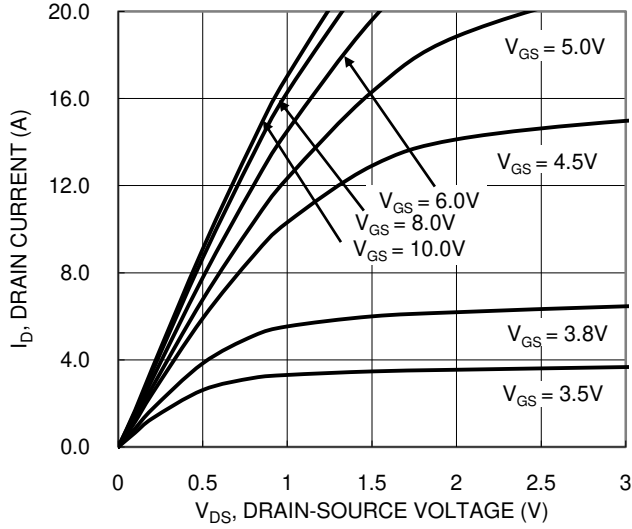


Figure 1. Typical Output Characteristic

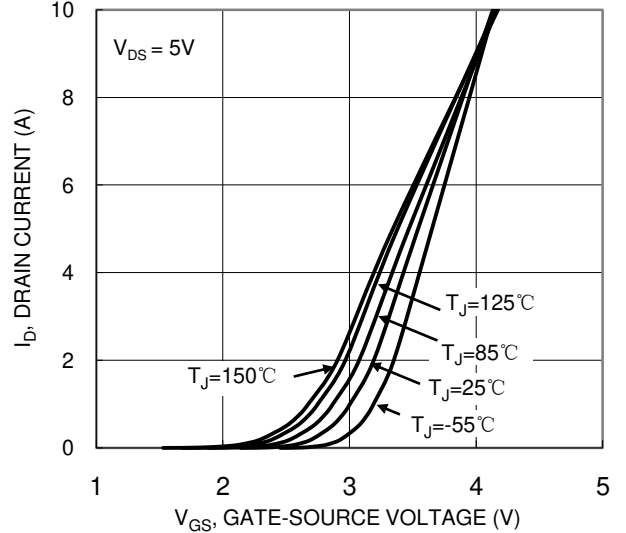


Figure 2. Typical Transfer Characteristic

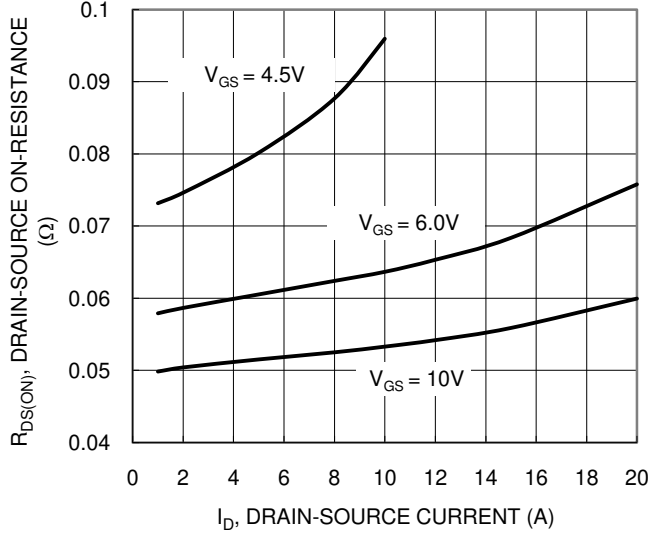


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

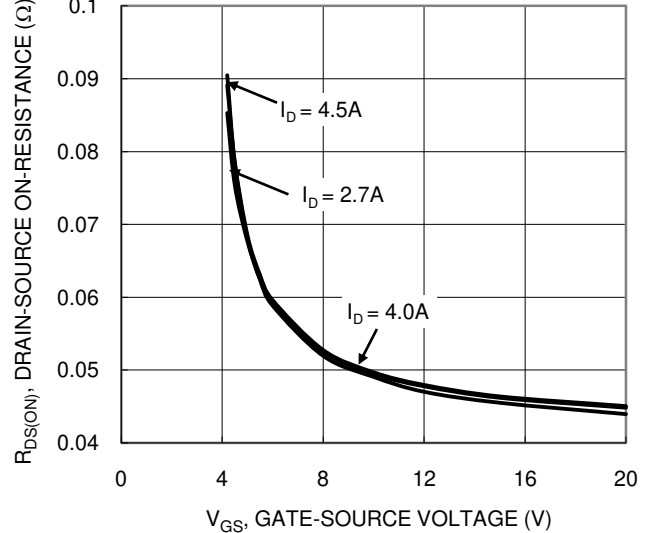


Figure 4. Typical Transfer Characteristic

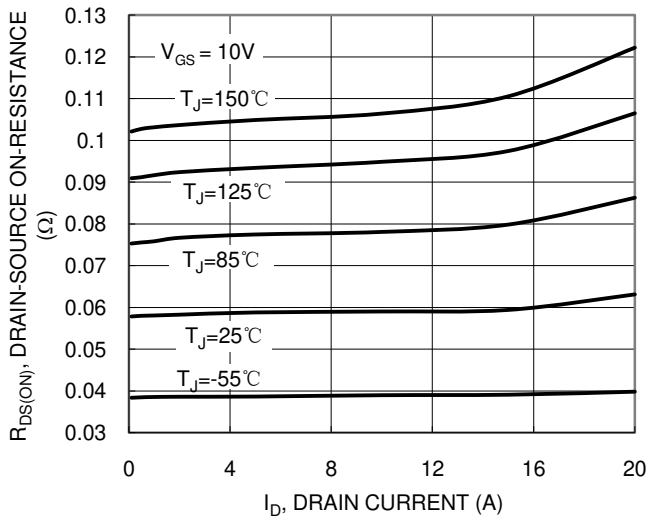


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

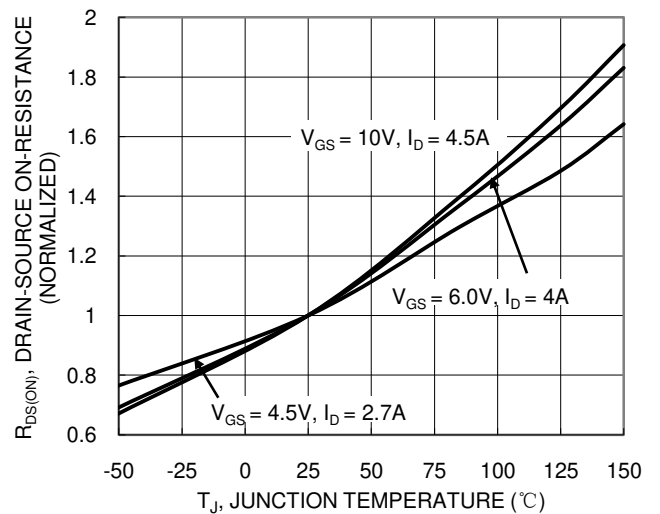


Figure 6. On-Resistance Variation with Junction Temperature

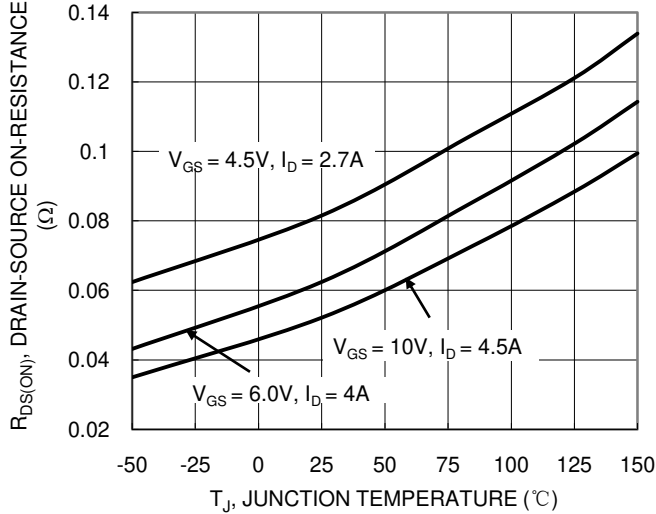


Figure 7. On-Resistance Variation with Junction Temperature

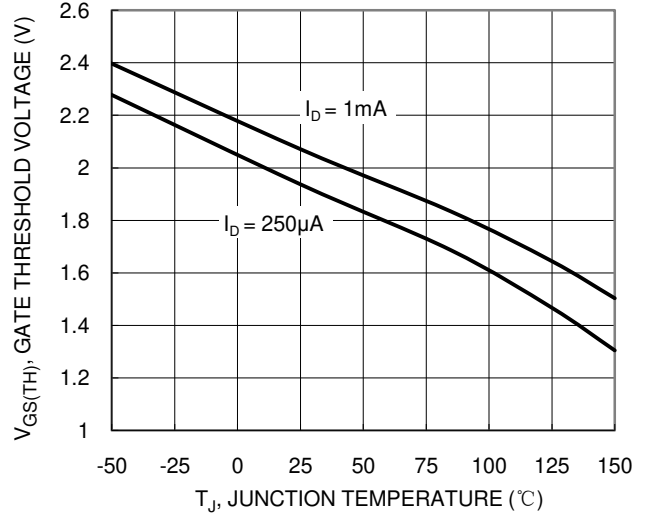


Figure 8. Gate Threshold Variation vs. Junction Temperature

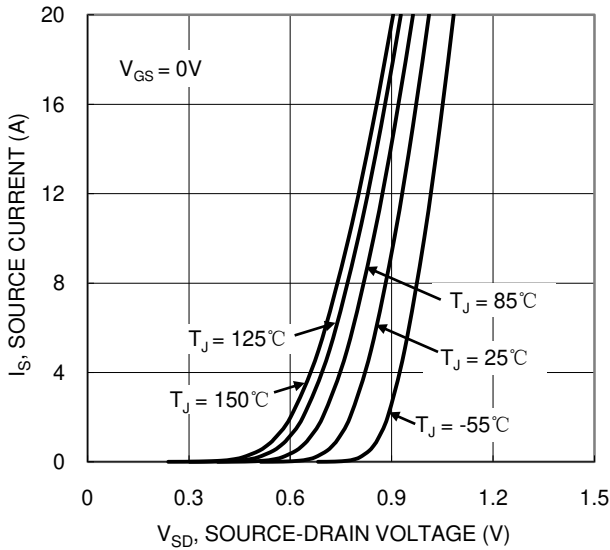


Figure 9. Diode Forward Voltage vs. Current

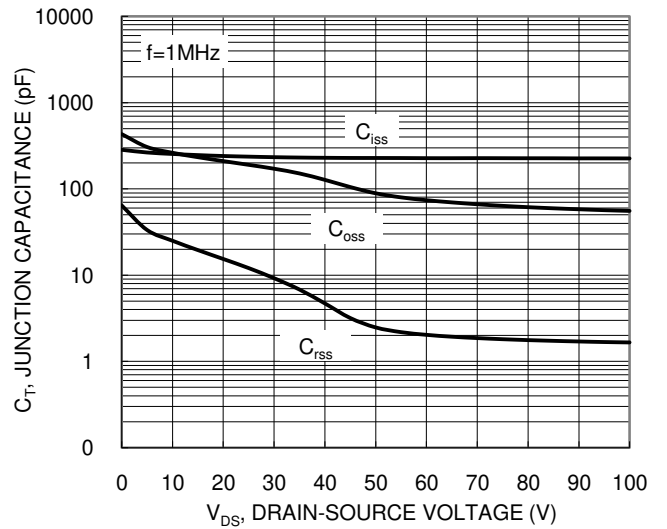


Figure 10. Typical Junction Capacitance

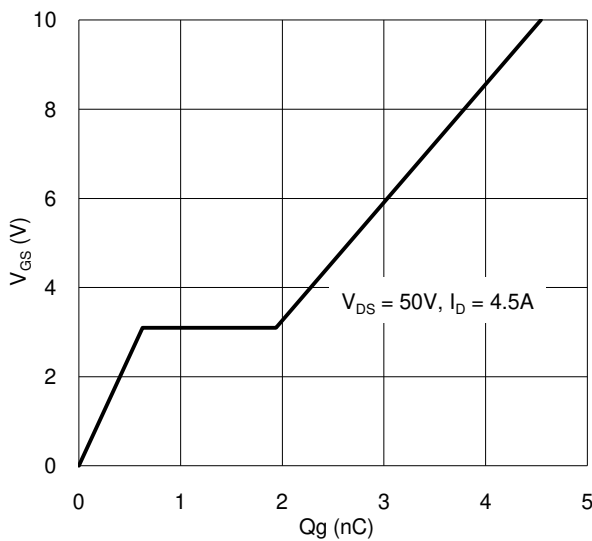


Figure 11. Gate Charge

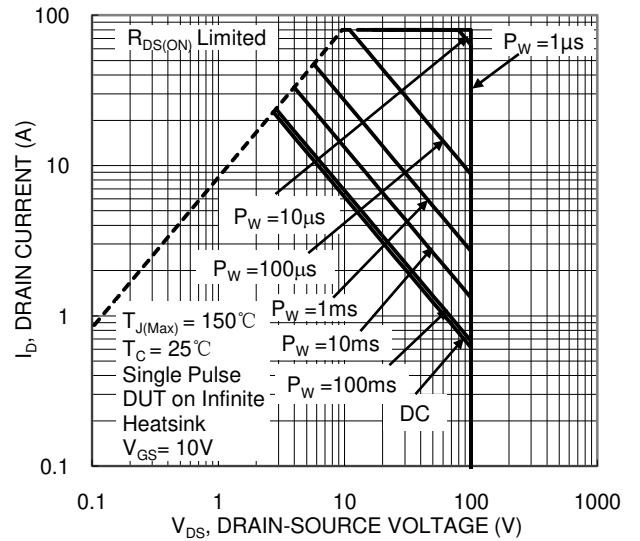


Figure 12. SOA, Safe Operation Area

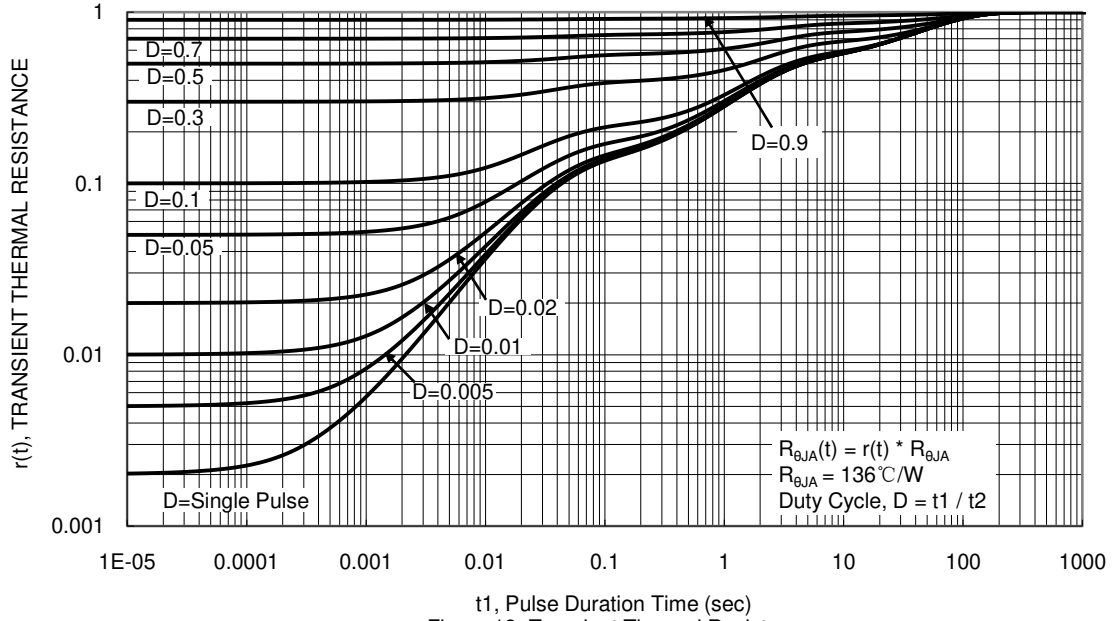
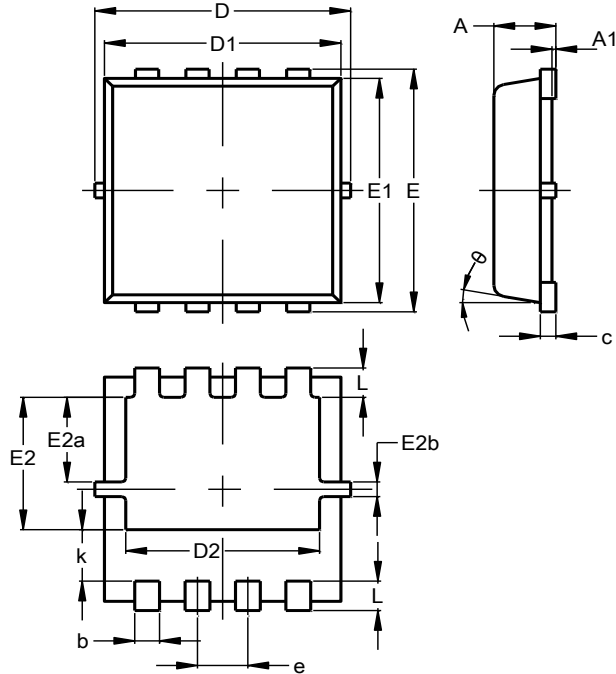


Figure 13. Transient Thermal Resistance

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI3333-8 (Type UX)**

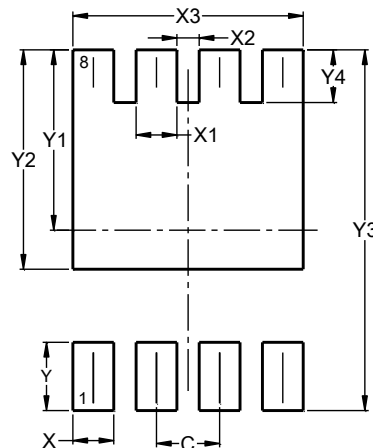


PowerDI3333-8 (Type UX)			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	--
b	0.25	0.40	0.32
c	0.10	0.25	0.15
D	3.20	3.40	3.30
D1	2.95	3.15	3.05
D2	2.30	2.70	2.50
E	3.20	3.40	3.30
E1	2.95	3.15	3.05
E2	1.60	2.00	1.80
E2a	0.95	1.35	1.15
E2b	0.10	0.30	0.20
e	0.65 BSC		
k	0.50	0.90	0.70
L	0.30	0.50	0.40
θ	0°	12°	10°
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI3333-8 (Type UX)**



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	0.420
X2	0.230
X3	2.370
Y	0.700
Y1	1.850
Y2	2.250
Y3	3.700
Y4	0.540

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